MOSFET – Single, N-Channel, Small Signal, SC-70

30 V, 270 mA

Features

- Low Gate Charge for Fast Switching
- Small Footprint 30% Smaller than TSOP–6
- ESD Protected Gate
- AEC-Q101 Qualified and PPAP Capable NVS4001N
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Low Side Load Switch
- Li-Ion Battery Supplied Devices Cell Phones, PDAs, DSC
- Buck Converters
- Level Shifts

MAXIMUM RATINGS (T_J = 25° C unless otherwise stated)

Param	Symbol	Value	Units		
Drain-to-Source Voltage			V _{DSS}	30	V
Gate-to-Source Voltage			V _{GS}	±20	V
Continuous Drain	Steady	T _A = 25 °C	۱ _D	270	mA
Current (Note 1)	State	T _A = 85 °C		200	
Power Dissipation (Note 1)	Steady State	T _A = 25 °C	PD	330	mW
Pulsed Drain Current t =10 μs			I _{DM}	800	mA
Operating Junction and Storage Temperature			T _J , T _{STG}	–55 to 150	°C
Source Current (Body Diode)			۱ _S	270	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Surface mounted on FR4 board using 1 in sq. pad size (Cu area = 1.127 in sq. [1 oz] including traces).

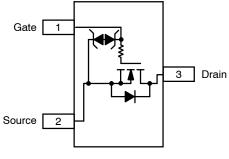


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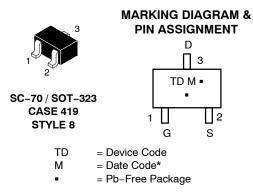
http://onsemi.com

V _{(BR)DSS}	R _{DS(on)} TYP	I _D Max	
30 V	1.0 Ω @ 4.0 V	270 mA	
	1.5 Ω @ 2.5 V	270 1114	

SC-70/SOT-323 (3 LEADS)



(Top View)



(Note: Microdot may be in either location) *Date Code orientation may vary depending

upon manufacturing location.

ORDERING INFORMATION

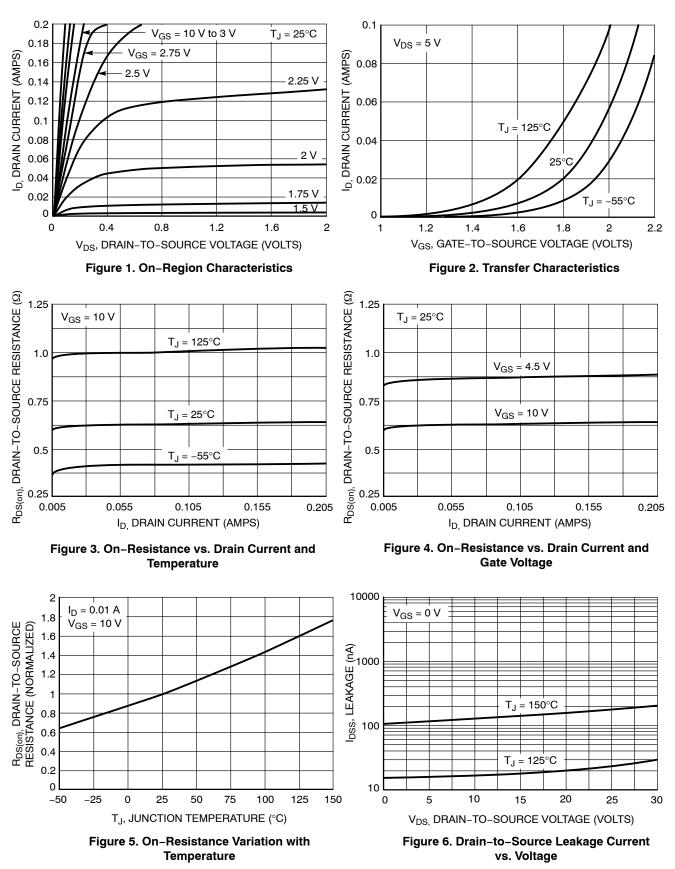
Device	Package	Shipping [†]
NTS4001NT1G	SC-70 (Pb-Free)	3000 / Tape & Reel
NVS4001NT1G	SC-70 (Pb-Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise stated)

Parameter	Symbol	Test Con	dition	Min	Тур	Мах	Unit
OFF CHARACTERISTICS		•			1		
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I _D = 100 µA		30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				60		mV/ °C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _E	_{DS} = 30 V			1.0	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 10 V$				±1.0	μΑ
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= 100 μA	0.8	1.2	1.5	V
Gate Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-3.4		mV/ °C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 4.0 V, I _I	V _{GS} = 4.0 V, I _D = 10 mA		1.0	1.5	Ω
		V _{GS} = 2.5 V, I _I	_O = 10 mA		1.5	2.0	
Forward Transconductance	9FS	V _{DS} = 3.0 V, I _D = 10 mA			80		mS
CHARGES AND CAPACITANCES							•
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1.0 MHz, V _{DS} = 5.0 V			20	33	pF
Output Capacitance	C _{OSS}				19	32	
Reverse Transfer Capacitance	C _{RSS}				7.25	12	
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 5.0 V, V _{DS} = 24 V, I _D = 0.1 A			0.9	1.3	nC
Threshold Gate Charge	Q _{G(TH)}				0.2		_
Gate-to-Source Charge	Q _{GS}				0.3		7
Gate-to-Drain Charge	Q _{GD}				0.2		
SWITCHING CHARACTERISTICS (No	te 3)						•
Turn-On Delay Time	td _(ON)				17		ns
Rise Time	tr	V _{GS} = 4.5 V, V _[סר = 5.0 V,		23		
Turn-Off Delay Time	td _(OFF)	$I_D = 10 \text{ mA}, R_G = 50 \Omega$			94		
Fall Time	tf				82		
DRAIN-SOURCE DIODE CHARACTE	RISTICS				•		
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		0.65	0.7	V
		l _S = 10 mA	T _J = 125°C		0.43		
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, } dI_S/dt$ $I_S = 10$	t = 8.0 A/μs, mA		5.0		ns
					1	1	

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
Switching characteristics are independent of operating junction temperatures.



TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

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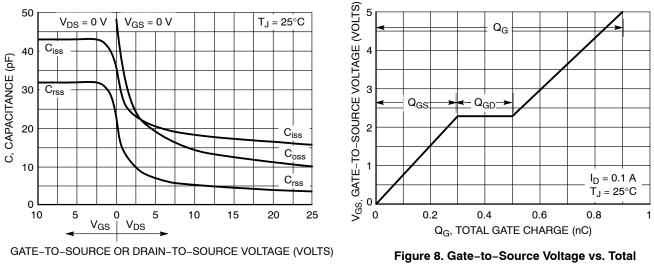


Figure 7. Capacitance Variation

Gate Charge

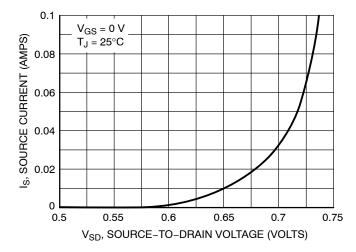
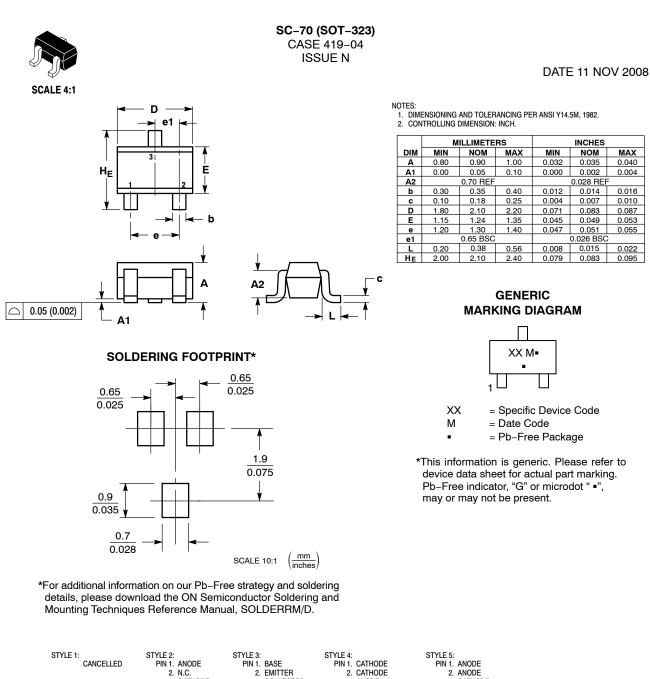


Figure 9. Diode Forward Voltage vs. Current





	3. CATHODE	3. COLLECTOR	3. ANODE	3. CATHODE	
Style 6:	STYLE 7:	STYLE 8:	STYLE 9:	Style 10:	STYLE 11:
Pin 1. Emitter	PIN 1. BASE	PIN 1. GATE	Pin 1. Anode	Pin 1. Cathode	PIN 1. CATHODE
2. Base	2. EMITTER	2. SOURCE	2. Cathode	2. Anode	2. CATHODE
3. Collector	3. COLLECTOR	3. DRAIN	3. Cathode-Anode	3. Anode-Cathode	3. CATHODE

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